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| FORM PTO-1449 INFORMATION DISCLOSURE CITATIONS IN AN APPLICATION | Atty Docket: | 02-6392/1D | Serial #: | 10/802522 |
| | Applicant: | Sukharev, Catabay, Lu | | |
| | Filing Date: | 2004.03.17 | Group: | 2815 |




U.S. PATENT DOCUMENTS


| Examiner Initial | Cite # | Document Number | Date | Name | Class | Sub-Class | Filing Date |
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FOREIGN PATENT DOCUMENTS

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|------------------|--------|-----------------|------|---------|-------|-----------|-------------|
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OTHER NON-PATENT DOCUMENTS

| Examiner Initial | Cite # | Author, title, date, pertinent pages, etc. |
|-----------------------------------------------------------------------------------|--------|--------------------------------------------------------------------------------------------------------------------------------------------------------|
|  | 1 | Hu et al., <i>Chemical vapor deposition copper interconnections and electromigration</i> , Electrochemical Society Proceedings, 97-25, 1514 (1997). |
|  | 2 | Hu et al., <i>Applied Physics Letters</i> , Vol. 74, Number 20, pp. 2945-2947 (1999). |
|  | 3 | Wang et al., <i>Stress-free polishing advances copper integration with ultralow-k dielectrics</i> , Solid State Technology, pp. 101-106, October 2001. |

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| Examiner  | Date Considered: 5/28/05 |
| EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant. | |